



## Semi Automatic BGA Rework Station Combining Automatic Mounting Functions with Rapid Heating and Cooling for Electronic Repair Tasks

Our Product Introduction

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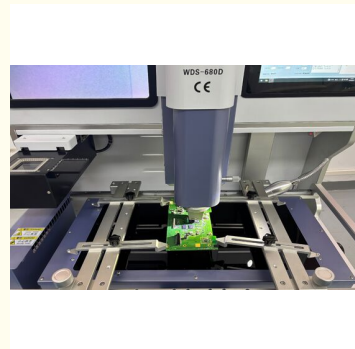
### Basic Information

- Place of Origin: CHINA
- Brand Name: WISDOMSHOW
- Certification: CE ISO FDA
- Model Number: WDS-880D/680D
- Minimum Order Quantity: 1
- Price: US\$16800

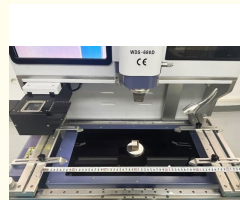
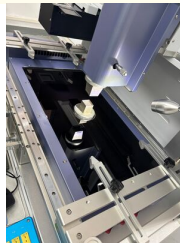


### Product Specification

- Dimensions: 450mm X 350mm X 300mm
- Core Components: PLC
- Suit Chips Size: 1\*1 120\*120mm
- Voltage: AC 220V
- Max Mouting Load: 150g
- Power Consumption: 800W
- Current: 50/60hz
- Function: Automatic Feeding Device
- Display: Digital LCD Display
- Mini Pcb Size: W10\*D10mm
- Applicable Chip Size: Max 80\*80mm Min 0.8\*0.8mm
- Temp Seasuring Interface: 1pcs
- Upper Heater Power: Max 1200W
- Heating: 3 Independent Heating Zones
- Power Supply Ac: Ac 220v ± 10% 50/60hz



### More Images



### Product Description

#### Automatic Infrared BGA Rework Station for Mobile Phone IC Repair

##### WDS-880D Main Features

- Integrated hot air head and mounting head design with automatic mounting, welding, and dismantling functions
- Upper air head features rapid heating system with uniform temperature distribution and fast cooling (50-80°C cooling capability), ideal for

Our Product

- lead-free soldering processes
- Lower heating zone utilizes infrared + hot air hybrid technology for fast PCB warm-up (10°C/S rate) with maintained temperature uniformity
- Three independent temperature zones (upper, lower, and infrared preheating) with synchronized automatic movement
- Motor-controlled lower temperature zone with vertical movement for PCB support
- High-precision slider system ensures accurate BGA and PCB board placement
- Original bottom preheating platform with German imported infrared gold-plated light tubes and anti-glare thermostatic glass (1800°C temperature resistance)
- 500 × 420mm preheating area with movable platform, clamping device, and cooling system in X-direction
- Motor-controlled X,Y axis movement for fast alignment and efficient space utilization
- Maximum clamping plate size of 590 × 400mm with no rework dead ends
- Dual joystick control with alignment lens and heating platform for precision alignment
- Built-in vacuum pump with  $\phi$  angle rotation and precision fine-tuning mounting nozzle
- Automatic suction and mounting height recognition with 10-gram pressure control and 0-pressure functions for smaller chips
- Color optical vision system with manual X,Y movement, spectral dual-color, magnification, and fine-tuning capabilities
- Chromatic aberration resolution device with auto-focus and software operation for BGA sizes up to 80 × 80mm
- Various alloy hot air nozzles with 360° rotation positioning
- Four temperature measurement ports for multi-point real-time monitoring and analysis
- Solid-state operation display for safe and reliable temperature control
- Automatic generation of SMT standard temperature disassembly curves for different environmental conditions
- Optional camera for observing tin ball melting points during the soldering process

### WDS-680D Technical Specifications

Parameter	Specification
Total Power	6000W
Upper Heating Power	1600W
Lower Heating Power	1600W
Infrared Heating Power	4000W Total IR Power
Power Supply	Two-phase 220V, 50/60Hz
Positioning Method	V-slot PCB fixing, laser positioning, motor-controlled X,Y axis
Temperature Control	High-precision K-type thermocouple closed loop control ( $\pm 1^\circ\text{C}$ accuracy)
Electrical Selection	PC control system, temperature control module, motion control board, Panasonic servo, stepper drive
Tin Spot Monitoring	External camera for monitoring tin ball melting process (optional)
MES System	Reserved MES port
Feeding Device	Automatic feeding device
Maximum PCB Size	590 × 400mm
Minimum PCB Size	10 × 10mm
Temperature Measurement Interface	4 ports
Chip Zoom Range	2 to 80 times
PCB Thickness	0.5-10mm
Applicable Chip Size	0.8 × 0.8 to 90 × 90mm
Minimum Chip Pitch	0.15mm
Maximum Mounting Load	500g
Mounting Accuracy	$\pm 0.01\text{mm}$
Overall Dimensions	820 × 706 × 1400mm
Machine Weight	Approximately 200KG
Other Features	Dual joystick operation, automatic & manual mode switching, 7-axis motorized motion control, dual-channel heating technology, MES port, smoke purification system



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